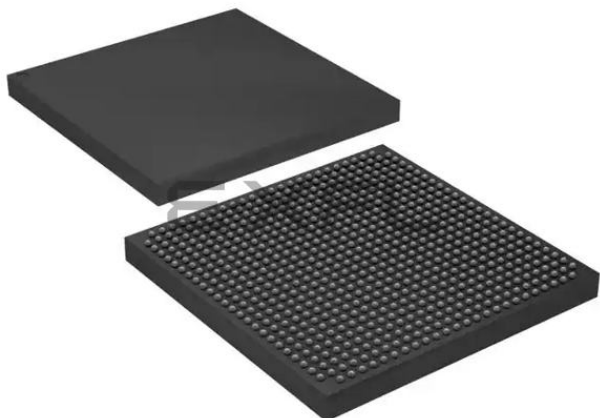




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2566
Number of Logic Elements/Cells	25660
Total RAM Bits	1944576
Number of I/O	473
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s25f672c7



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Section I. Stratix Device Family Data Sheet

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Table 1–1. Stratix Device Features — EP1S10, EP1S20, EP1S25, EP1S30

Feature	EP1S10	EP1S20	EP1S25	EP1S30
LEs	10,570	18,460	25,660	32,470
M512 RAM blocks (32×18 bits)	94	194	224	295
M4K RAM blocks (128×36 bits)	60	82	138	171
M-RAM blocks ($4K \times 144$ bits)	1	2	2	4
Total RAM bits	920,448	1,669,248	1,944,576	3,317,184
DSP blocks	6	10	10	12
Embedded multipliers (1)	48	80	80	96
PLLs	6	6	6	10
Maximum user I/O pins	426	586	706	726

Table 1–2. Stratix Device Features — EP1S40, EP1S60, EP1S80

Feature	EP1S40	EP1S60	EP1S80
LEs	41,250	57,120	79,040
M512 RAM blocks (32×18 bits)	384	574	767
M4K RAM blocks (128×36 bits)	183	292	364
M-RAM blocks ($4K \times 144$ bits)	4	6	9
Total RAM bits	3,423,744	5,215,104	7,427,520
DSP blocks	14	18	22
Embedded multipliers (1)	112	144	176
PLLs	12	12	12
Maximum user I/O pins	822	1,022	1,238

Note to Tables 1–1 and 1–2:

- (1) This parameter lists the total number of 9×9 -bit multipliers for each device. For the total number of 18×18 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 2. For the total number of 36×36 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 8.

can drive other R8 interconnects to extend their range as well as C8 interconnects for row-to-row connections. One R8 interconnect is faster than two R4 interconnects connected together.

R24 row interconnects span 24 LABs and provide the fastest resource for long row connections between LABs, TriMatrix memory, DSP blocks, and IOEs. The R24 row interconnects can cross M-RAM blocks. R24 row interconnects drive to other row or column interconnects at every fourth LAB and do not drive directly to LAB local interconnects. R24 row interconnects drive LAB local interconnects via R4 and C4 interconnects. R24 interconnects can drive R24, R4, C16, and C4 interconnects.

The column interconnect operates similarly to the row interconnect and vertically routes signals to and from LABs, TriMatrix memory, DSP blocks, and IOEs. Each column of LABs is served by a dedicated column interconnect, which vertically routes signals to and from LABs, TriMatrix memory and DSP blocks, and horizontal IOEs. These column resources include:

- LUT chain interconnects within an LAB
- Register chain interconnects within an LAB
- C4 interconnects traversing a distance of four blocks in up and down direction
- C8 interconnects traversing a distance of eight blocks in up and down direction
- C16 column interconnects for high-speed vertical routing through the device

Stratix devices include an enhanced interconnect structure within LABs for routing LE output to LE input connections faster using LUT chain connections and register chain connections. The LUT chain connection allows the combinatorial output of an LE to directly drive the fast input of the LE right below it, bypassing the local interconnect. These resources can be used as a high-speed connection for wide fan-in functions from LE 1 to LE 10 in the same LAB. The register chain connection allows the register output of one LE to connect directly to the register input of the next LE in the LAB for fast shift registers. The Quartus II Compiler automatically takes advantage of these resources to improve utilization and performance. [Figure 2-10](#) shows the LUT chain and register chain interconnects.

M4K RAM blocks support byte writes when the write port has a data width of 16, 18, 32, or 36 bits. The byte enables allow the input data to be masked so the device can write to specific bytes. The unwritten bytes retain the previous written value. Table 2-7 summarizes the byte selection.

Table 2-7. Byte Enable for M4K Blocks <i>Notes (1), (2)</i>		
byteena[3..0]	datain ×18	datain ×36
[0] = 1	[8..0]	[8..0]
[1] = 1	[17..9]	[17..9]
[2] = 1	–	[26..18]
[3] = 1	–	[35..27]

Notes to Table 2-7:

- (1) Any combination of byte enables is possible.
- (2) Byte enables can be used in the same manner with 8-bit words, i.e., in ×16 and ×32 modes.

The M4K RAM blocks allow for different clocks on their inputs and outputs. Either of the two clocks feeding the block can clock M4K RAM block registers (renwe, address, byte enable, datain, and output registers). Only the output register can be bypassed. The eight labclk signals or local interconnects can drive the control signals for the A and B ports of the M4K RAM block. LEs can also control the clock_a, clock_b, renwe_a, renwe_b, clr_a, clr_b, clocken_a, and clocken_b signals, as shown in Figure 2-17.

The R4, R8, C4, C8, and direct link interconnects from adjacent LABs drive the M4K RAM block local interconnect. The M4K RAM blocks can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 10 direct link input connections to the M4K RAM Block are possible from the left adjacent LABs and another 10 possible from the right adjacent LAB. M4K RAM block outputs can also connect to left and right LABs through 10 direct link interconnects each. Figure 2-18 shows the M4K RAM block to logic array interface.

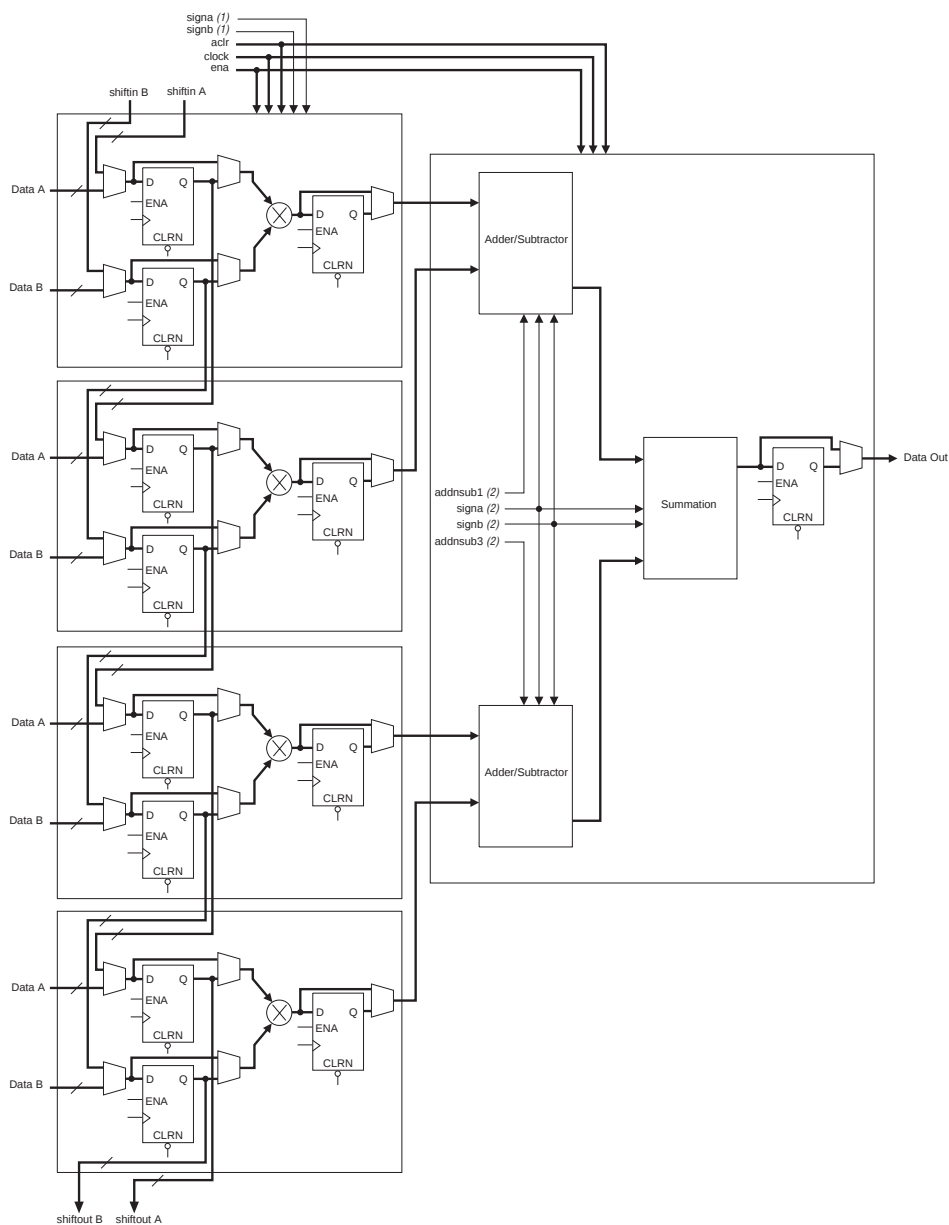
Table 2–11. M-RAM Combined Byte Selection for $\times 144$ Mode *Notes (1), (2)*

byteena[15..0]	datain $\times 144$
[0] = 1	[8..0]
[1] = 1	[17..9]
[2] = 1	[26..18]
[3] = 1	[35..27]
[4] = 1	[44..36]
[5] = 1	[53..45]
[6] = 1	[62..54]
[7] = 1	[71..63]
[8] = 1	[80..72]
[9] = 1	[89..81]
[10] = 1	[98..90]
[11] = 1	[107..99]
[12] = 1	[116..108]
[13] = 1	[125..117]
[14] = 1	[134..126]
[15] = 1	[143..135]

Notes to Tables 2–10 and 2–11:

- (1) Any combination of byte enables is possible.
- (2) Byte enables can be used in the same manner with 8-bit words, i.e., in $\times 16$, $\times 32$, $\times 64$, and $\times 128$ modes.

Similar to all RAM blocks, M-RAM blocks can have different clocks on their inputs and outputs. All input registers—renwe, datain, address, and byte enable registers—are clocked together from either of the two clocks feeding the block. The output register can be bypassed. The eight labclk signals or local interconnect can drive the control signals for the A and B ports of the M-RAM block. LEs can also control the clock_a, clock_b, renwe_a, renwe_b, clr_a, clr_b, clocken_a, and clocken_b signals as shown in Figure 2–19.

Figure 2–39. Four-Multipliers Adder Mode**Notes to Figure 2–39:**

- (1) These signals are not registered or registered once to match the data path pipeline.
- (2) These signals are not registered, registered once, or registered twice for latency to match the data path pipeline.

clock signals are routed from LAB row clocks and are generated from specific LAB rows at the DSP block interface. The LAB row source for control signals, data inputs, and outputs is shown in [Table 2–17](#).

Table 2–17. DSP Block Signal Sources & Destinations			
LAB Row at Interface	Control Signals Generated	Data Inputs	Data Outputs
1	signa	A1 [17..0]	OA [17..0]
2	aclr0 accum_sload0	B1 [17..0]	OB [17..0]
3	addnsb1 clock0 ena0	A2 [17..0]	OC [17..0]
4	aclr1 clock1 ena1	B2 [17..0]	OD [17..0]
5	aclr2 clock2 ena2	A3 [17..0]	OE [17..0]
6	sign_b clock3 ena3	B3 [17..0]	OF [17..0]
7	clear3 accum_sload1	A4 [17..0]	OG [17..0]
8	addnsb3	B4 [17..0]	OH [17..0]

PLLs & Clock Networks

Stratix devices provide a hierarchical clock structure and multiple PLLs with advanced features. The large number of clocking resources in combination with the clock synthesis precision provided by enhanced and fast PLLs provides a complete clock management solution.

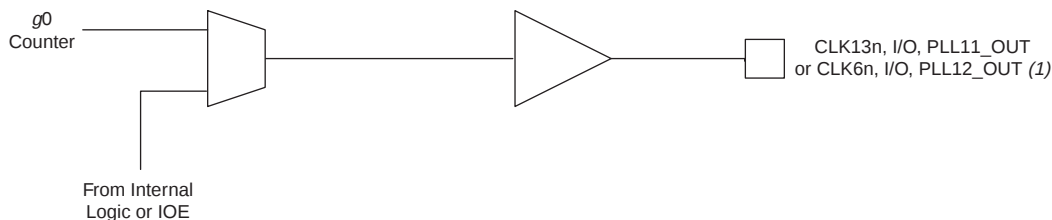
Global & Hierarchical Clocking

Stratix devices provide 16 dedicated global clock networks, 16 regional clock networks (four per device quadrant), and 8 dedicated fast regional clock networks (for EP1S10, EP1S20, and EP1S25 devices), and 16 dedicated fast regional clock networks (for EP1S30 EP1S40, and EP1S60, and EP1S80 devices). These clocks are organized into a hierarchical clock structure that allows for up to 22 clocks per device region with low skew and delay. This hierarchical clocking scheme provides up to 48 unique clock domains within Stratix devices.

Table 2–20. I/O Standards Supported for Enhanced PLL Pins (Part 2 of 2)

I/O Standard	Input			Output
	INCLK	FBIN	PLENABLE	EXTCLK
1.5-V HSTL Class II	✓	✓		✓
1.8-V HSTL Class I	✓	✓		✓
1.8-V HSTL Class II	✓	✓		✓
SSTL-18 Class I	✓	✓		✓
SSTL-18 Class II	✓	✓		✓
SSTL-2 Class I	✓	✓		✓
SSTL-2 Class II	✓	✓		✓
SSTL-3 Class I	✓	✓		✓
SSTL-3 Class II	✓	✓		✓
AGP (1× and 2×)	✓	✓		✓
CTT	✓	✓		✓

Enhanced PLLs 11 and 12 support one single-ended output each (see [Figure 2–56](#)). These outputs do not have their own VCC and GND signals. Therefore, to minimize jitter, do not place switching I/O pins next to this output pin.

Figure 2–56. External Clock Outputs for Enhanced PLLs 11 & 12

Note to Figure 2–56:

(1) For PLL 11, this pin is CLK13n; for PLL 12 this pin is CLK7n.

Stratix devices can drive any enhanced PLL driven through the global clock or regional clock network to any general I/O pin as an external output clock. The jitter on the output clock is not guaranteed for these cases.

VCO period from up to eight taps for individual fine step selection. Also, each clock output counter can use a unique initial count setting to achieve individual coarse shift selection in steps of one VCO period. The combination of coarse and fine shifts allows phase shifting for the entire input clock period.

The equation to determine the precision of the phase shifting in degrees is: $45^\circ \div \text{post-scale counter value}$. Therefore, the maximum step size is 45° , and smaller steps are possible depending on the multiplication and division ratio necessary on the output counter port.

This type of phase shift provides the highest precision since it is the least sensitive to process, supply, and temperature variation.

Clock Delay

In addition to the phase shift feature, the ability to fine tune the Δt clock delay provides advanced time delay shift control on each of the four PLL outputs. There are time delays for each post-scale counter (e , g , or l) from the PLL, the n counter, and m counter. Each of these can shift in 250-ps increments for a range of 3.0 ns. The m delay shifts all outputs earlier in time, while n delay shifts all outputs later in time. Individual delays on post-scale counters (e , g , and l) provide positive delay for each output. [Table 2-21](#) shows the combined delay for each output for normal or zero delay buffer mode where Δt_e , Δt_g , or Δt_l is unique for each PLL output.

The t_{OUTPUT} for a single output can range from -3 ns to $+6$ ns. The total delay shift difference between any two PLL outputs, however, must be less than ± 3 ns. For example, shifts on two outputs of -1 and $+2$ ns is allowed, but not -1 and $+2.5$ ns because these shifts would result in a difference of 3.5 ns. If the design uses external feedback, the Δt_e delay will remove delay from outputs, represented by a negative sign (see [Table 2-21](#)). This effect occurs because the Δt_e delay is then part of the feedback loop.

Table 2-21. Output Clock Delay for Enhanced PLLs

Normal or Zero Delay Buffer Mode	External Feedback Mode
$\Delta t_{e\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_e$	$\Delta t_{e\text{OUTPUT}} = \Delta t_n - \Delta t_m - \Delta t_e$ (1)
$\Delta t_{g\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_g$	$\Delta t_{g\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_g$
$\Delta t_{l\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_l$	$\Delta t_{l\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_l$

Note to [Table 2-21](#):

(1) Δt_e removes delay from outputs in external feedback mode.

Stratix devices have an I/O interconnect similar to the R4 and C4 interconnect to drive high-fanout signals to and from the I/O blocks. There are 16 signals that drive into the I/O blocks composed of four output enables `io_boe[3..0]`, four clock enables `io_bce[3..0]`, four clocks `io_bclk[3..0]`, and four clear signals `io_bclr[3..0]`. The pin's `datain` signals can drive the IO interconnect, which in turn drives the logic array or other I/O blocks. In addition, the control and data signals can be driven from the logic array, providing a slower but more flexible routing resource. The row or column IOE clocks, `io_clk[7..0]`, provide a dedicated routing resource for low-skew, high-speed clocks. I/O clocks are generated from regional, global, or fast regional clocks (see “PLLs & Clock Networks” on page 2-73). Figure 2-62 illustrates the signal paths through the I/O block.

Figure 2-62. Signal Path through the I/O Block

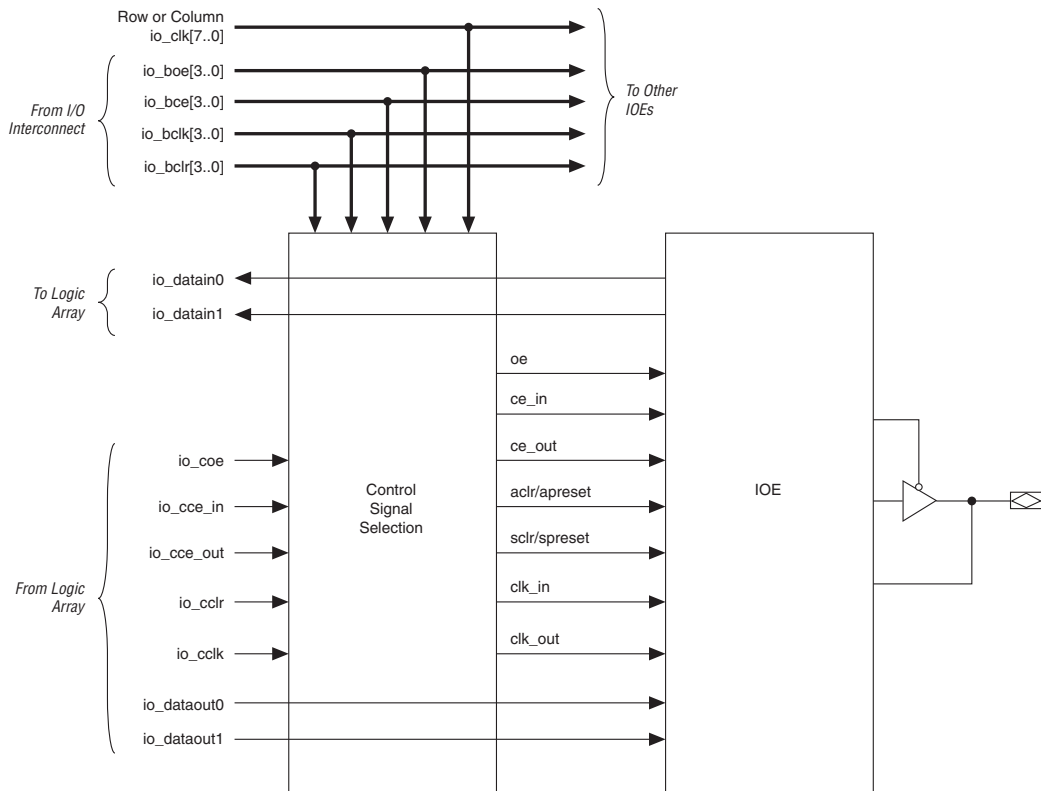


Table 4–36. Stratix Performance (Part 2 of 2) Notes (1), (2)

Applications		Resources Used			Performance				
		LEs	TriMatrix Memory Blocks	DSP Blocks	-5 Speed Grade	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Units
TriMatrix memory M-RAM block	True dual-port RAM 16K × 36 bit	0	1	0	269.83	237.69	206.82	175.74	MHz
	Single port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	180.83	MHz
	Simple dual-port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	180.83	MHz
	True dual-port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	180.83	MHz
	Single port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	187.26	MHz
	Simple dual-port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	187.26	MHz
	True dual-port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	187.26	MHz
DSP block	9 × 9-bit multiplier (3)	0	0	1	335.0	293.94	255.68	217.24	MHz
	18 × 18-bit multiplier (4)	0	0	1	278.78	237.41	206.52	175.50	MHz
	36 × 36-bit multiplier (4)	0	0	1	148.25	134.71	117.16	99.59	MHz
	36 × 36-bit multiplier (5)	0	0	1	278.78	237.41	206.52	175.5	MHz
	18-bit, 4-tap FIR filter	0	0	1	278.78	237.41	206.52	175.50	MHz
Larger Designs	8-bit, 16-tap parallel FIR filter	58	0	4	141.26	133.49	114.88	100.28	MHz
	8-bit, 1,024-point FFT function	870	5	1	261.09	235.51	205.21	175.22	MHz

Notes to Table 4–36:

- (1) These design performance numbers were obtained using the Quartus II software.
- (2) Numbers not listed will be included in a future version of the data sheet.
- (3) This application uses registered inputs and outputs.
- (4) This application uses registered multiplier input and output stages within the DSP block.
- (5) This application uses registered multiplier input, pipeline, and output stages within the DSP block.

Table 4–59. EP1S10 External I/O Timing on Row Pins Using Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.161		2.336		2.685		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.434	4.889	2.434	5.226	2.434	5.643	NA	NA	ns
t_{XZ}	2.461	4.493	2.461	5.282	2.461	5.711	NA	NA	ns
t_{ZX}	2.461	4.493	2.461	5.282	2.461	5.711	NA	NA	ns
t_{INSUPLL}	1.057		1.172		1.315		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.327	2.773	1.327	2.848	1.327	2.940	NA	NA	ns
t_{XZPLL}	1.354	2.827	1.354	2.904	1.354	3.008	NA	NA	ns
t_{ZXPLL}	1.354	2.827	1.354	2.904	1.354	3.008	NA	NA	ns

Table 4–60. EP1S10 External I/O Timing on Row Pins Using Global Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.787		1.944		2.232		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.647	5.263	2.647	5.618	2.647	6.069	NA	NA	ns
t_{XZ}	2.674	5.317	2.674	5.674	2.674	6.164	NA	NA	ns
t_{ZX}	2.674	5.317	2.674	5.674	2.674	6.164	NA	NA	ns
t_{INSUPLL}	1.371		1.1472		1.654		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.144	2.459	1.144	2.548	1.144	2.601	NA	NA	ns
t_{XZPLL}	1.171	2.513	1.171	2.604	1.171	2.669	NA	NA	ns
t_{ZXPLL}	1.171	2.513	1.171	2.604	1.171	2.669	NA	NA	ns

Note to Tables 4–55 to 4–60:

(1) Only EP1S25, EP1S30, and EP1S40 have speed grade of -8.

Tables 4–67 through 4–72 show the external timing parameters on column and row pins for EP1S25 devices.

Table 4–67. EP1S25 External I/O Timing on Column Pins Using Fast Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.412		2.613		2.968		3.468		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.196	4.475	2.196	4.748	2.196	5.118	2.196	5.603	ns
t_{XZ}	2.136	4.349	2.136	4.616	2.136	4.994	2.136	5.488	ns
t_{ZX}	2.136	4.349	2.136	4.616	2.136	4.994	2.136	5.488	ns

Table 4–68. EP1S25 External I/O Timing on Column Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.535		1.661		1.877		2.125		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.739	5.396	2.739	5.746	2.739	6.262	2.739	6.946	ns
t_{XZ}	2.679	5.270	2.679	5.614	2.679	6.138	2.679	6.831	ns
t_{ZX}	2.679	5.270	2.679	5.614	2.679	6.138	2.679	6.831	ns
t_{INSUPLL}	0.934		0.980		1.092		1.231		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.316	2.733	1.316	2.839	1.316	2.921	1.316	3.110	ns
t_{XZPLL}	1.256	2.607	1.256	2.707	1.256	2.797	1.256	2.995	ns
t_{ZXPLL}	1.256	2.607	1.256	2.707	1.256	2.797	1.256	2.995	ns

Tables 4–73 through 4–78 show the external timing parameters on column and row pins for EP1S30 devices.

Table 4–73. EP1S30 External I/O Timing on Column Pins Using Fast Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.502		2.680		3.062		3.591		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.473	4.965	2.473	5.329	2.473	5.784	2.473	6.392	ns
t_{XZ}	2.413	4.839	2.413	5.197	2.413	5.660	2.413	6.277	ns
t_{ZX}	2.413	4.839	2.413	5.197	2.413	5.660	2.413	6.277	ns

Table 4–74. EP1S30 External I/O Timing on Column Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.286		2.426		2.769		3.249		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.641	5.225	2.641	5.629	2.641	6.130	2.641	6.796	ns
t_{XZ}	2.581	5.099	2.581	5.497	2.581	6.006	2.581	6.681	ns
t_{ZX}	2.581	5.099	2.581	5.497	2.581	6.006	2.581	6.681	ns
t_{INSUPLL}	1.200		1.185		1.344		1.662		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.108	2.367	1.108	2.534	1.108	2.569	1.108	2.517	ns
t_{XZPLL}	1.048	2.241	1.048	2.402	1.048	2.445	1.048	2.402	ns
t_{ZXPLL}	1.048	2.241	1.048	2.402	1.048	2.445	1.048	2.402	ns

Table 4–75. EP1S30 External I/O Timing on Column Pins Using Global Clock Networks (Part 1 of 2)

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.935		2.029		2.310		2.709		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.814	5.532	2.814	5.980	2.814	6.536	2.814	7.274	ns

Table 4–83. EP1S40 External I/O Timing on Row Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.349		2.526		2.898		2.952		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.725	5.381	2.725	5.784	2.725	6.290	2.725	7.426	ns
t_{XZ}	2.752	5.435	2.752	5.840	2.752	6.358	2.936	7.508	ns
t_{ZX}	2.752	5.435	2.752	5.840	2.752	6.358	2.936	7.508	ns
t_{INSUPLL}	1.328		1.322		1.605		1.883		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.169	2.502	1.169	2.698	1.169	2.650	1.169	2.691	ns
t_{XZPLL}	1.196	2.556	1.196	2.754	1.196	2.718	1.196	2.773	ns
t_{ZXPLL}	1.196	2.556	1.196	2.754	1.196	2.718	1.196	2.773	ns

Table 4–84. EP1S40 External I/O Timing on Row Pins Using Global Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.020		2.171		2.491		2.898		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.912	5.710	2.912	6.139	2.912	6.697	2.931	7.480	ns
t_{XZ}	2.939	5.764	2.939	6.195	2.939	6.765	2.958	7.562	ns
t_{ZX}	2.939	5.764	2.939	6.195	2.939	6.765	2.958	7.562	ns
t_{INSUPLL}	1.370		1.368		1.654		1.881		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.144	2.460	1.144	2.652	1.144	2.601	1.170	2.693	ns
t_{XZPLL}	1.171	2.514	1.171	2.708	1.171	2.669	1.197	2.775	ns
t_{ZXPLL}	1.171	2.514	1.171	2.708	1.171	2.669	1.197	2.775	ns

Tables 4–85 through 4–90 show the external timing parameters on column and row pins for EP1S60 devices.

Table 4–85. EP1S60 External I/O Timing on Column Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	3.029		3.277		3.733		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.446	4.871	2.446	5.215	2.446	5.685	NA	NA	ns
t_{XZ}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns
t_{ZX}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns

Table 4–86. EP1S60 External I/O Timing on Column Pins Using Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.491		2.691		3.060		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.767	5.409	2.767	5.801	2.767	6.358	NA	NA	ns
t_{XZ}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{ZX}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{INSUPLL}	1.233		1.270		1.438		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.078	2.278	1.078	2.395	1.078	2.428	NA	NA	ns
t_{XZPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns
t_{ZXPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns

Table 4–117. Stratix Maximum Input Clock Rate for CLK[7..4] & CLK[15..12] Pins in Wire-Bond Packages (Part 2 of 2)

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
GTL+	250	200	200	MHz
SSTL-3 Class I	300	250	250	MHz
SSTL-3 Class II	300	250	250	MHz
SSTL-2 Class I	300	250	250	MHz
SSTL-2 Class II	300	250	250	MHz
SSTL-18 Class I	300	250	250	MHz
SSTL-18 Class II	300	250	250	MHz
1.5-V HSTL Class I	300	180	180	MHz
1.5-V HSTL Class II	300	180	180	MHz
1.8-V HSTL Class I	300	180	180	MHz
1.8-V HSTL Class II	300	180	180	MHz
3.3-V PCI	422	390	390	MHz
3.3-V PCI-X 1.0	422	390	390	MHz
Compact PCI	422	390	390	MHz
AGP 1×	422	390	390	MHz
AGP 2×	422	390	390	MHz
CTT	250	180	180	MHz
Differential 1.5-V HSTL C1	300	180	180	MHz
LVPECL (1)	422	400	400	MHz
PCML (1)	215	200	200	MHz
LVDS (1)	422	400	400	MHz
HyperTransport technology (1)	422	400	400	MHz

Table 4–118. Stratix Maximum Input Clock Rate for CLK[0, 2, 9, 11] Pins & FPLL[10..7]CLK Pins in Wire-Bond Packages (Part 1 of 2)

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
LVTTL	422	390	390	MHz
2.5 V	422	390	390	MHz
1.8 V	422	390	390	MHz
1.5 V	422	390	390	MHz

process and operating conditions. Run the timing analyzer in the Quartus II software at the fast and slow operating conditions to see the phase shift range that is achieved below these frequencies.

Table 4–135. Stratix DLL Low Frequency Limit for Full Phase Shift

Phase Shift	Minimum Frequency for Full Phase Shift	Unit
72°	119	MHz
90°	149	MHz

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